

Flip-Chip Mounting PCB

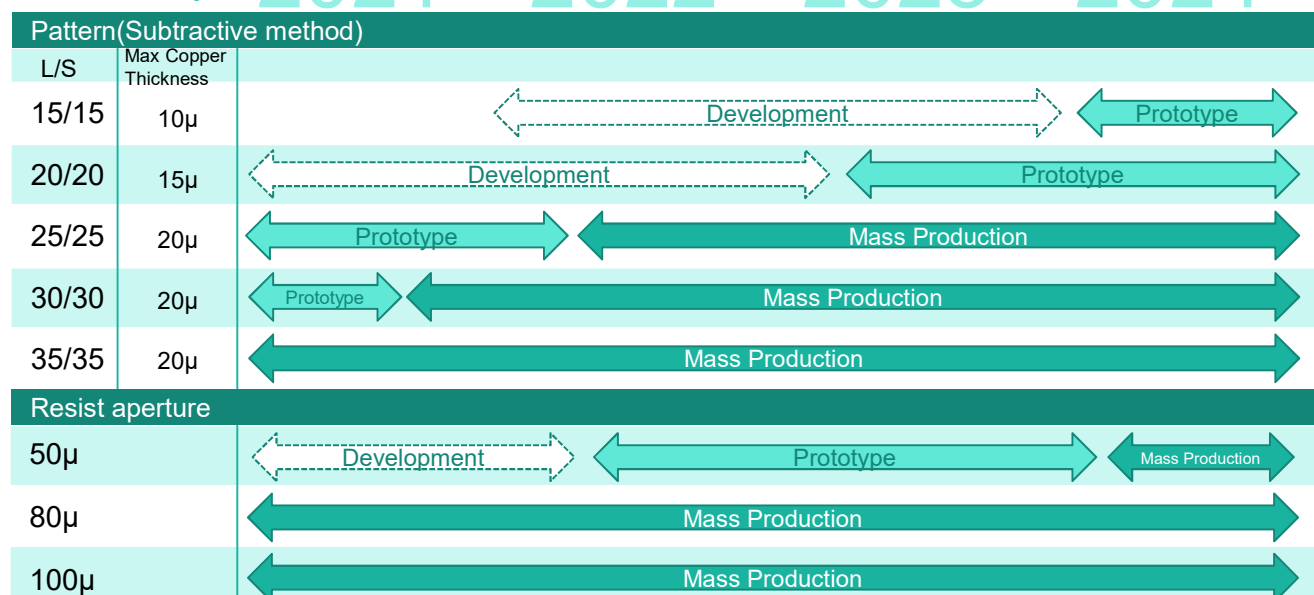


High-density Advanced fine circuit pattern and Flip-chip mounting PCB for Semiconductor packages.

High-density advanced semiconductor packages are used in 5G/mobile communication equipment/server/FC-BGA. We enable to produce low cost fine patterning by our own subtractive method technology. We add direct imaging exposure system to existing contact exposure system, it makes the pattern more high-density and high accuracy.

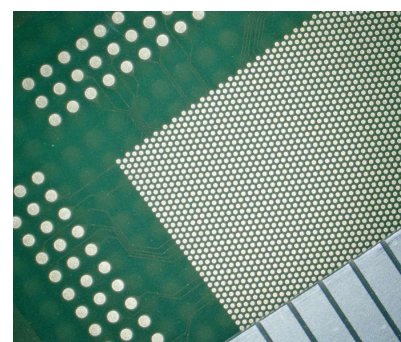
Technology Roadmap

2021 2022 2023 2024



Design Rules

	Fine 1 (Direct imaging)	Fine 2 (Contact exposure)	Standard
Pattern position accuracy (to through hole)	±10μ	±35μ	±50μ
Solder resist position accuracy (to pattern)	±30μ	±50μ	±75μ



Flip-chip BGA



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